

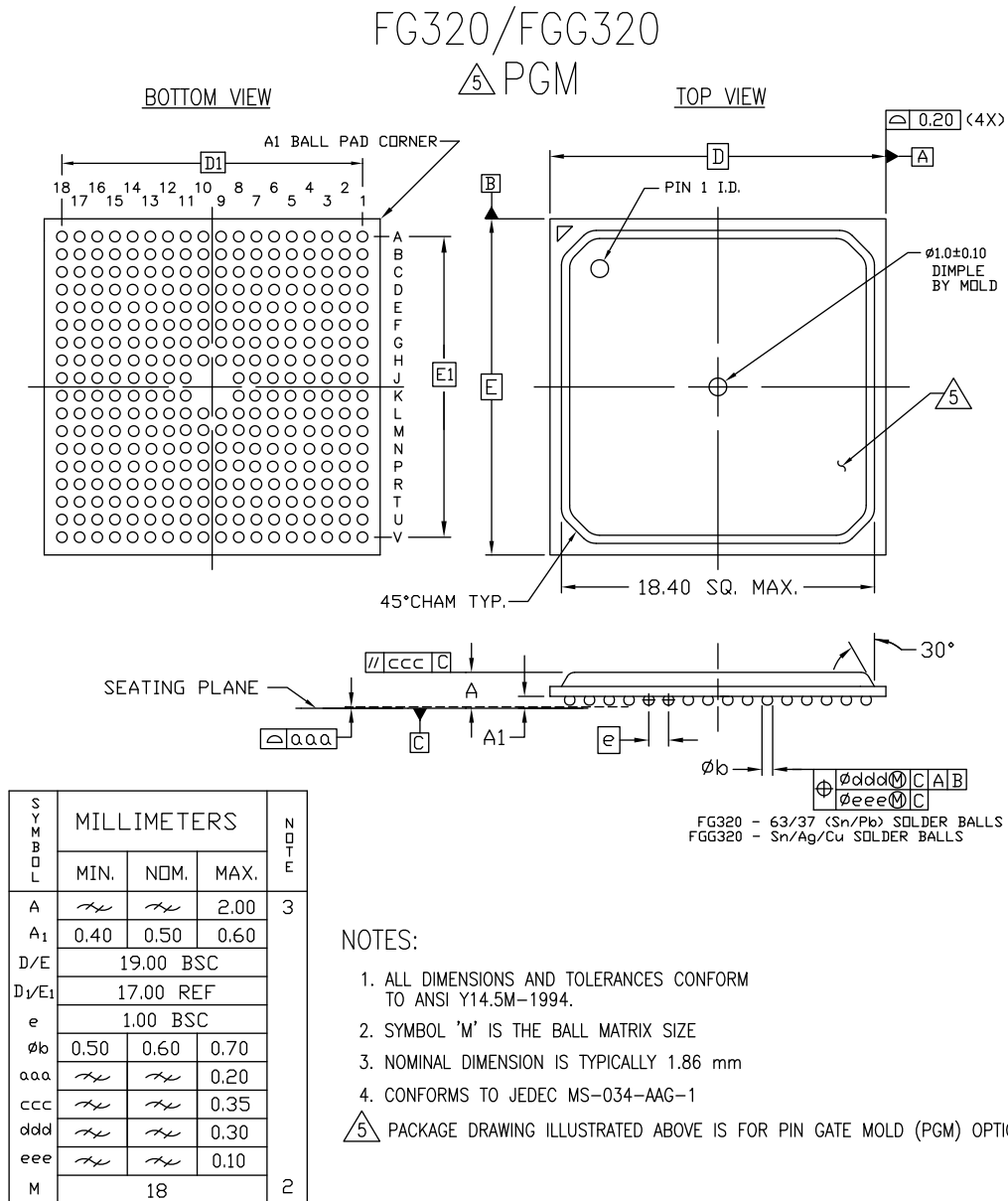
SYMBOL	MILLIMETERS			NOTE
	MIN.	NOM.	MAX.	
A	\approx	\approx	2.00	3
A ₁	0.40	0.50	0.60	
D/E	19.00 BSC			
D ₁ /E ₁	17.00 REF			2
e	1.00 BSC			
ϕ b	0.50	0.60	0.70	
aaa	\approx	\approx	0.20	
ccc	\approx	\approx	0.35	
ddd	\approx	\approx	0.30	
eee	\approx	\approx	0.10	
M	18			

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
2. SYMBOL 'M' IS THE BALL MATRIX SIZE
3. NOMINAL DIMENSION IS TYPICALLY 1.86 mm
4. CONFORMS TO JEDEC MS-034-AAG-1
- △5 PACKAGE DRAWING ILLUSTRATED ABOVE IS FOR CORNER GATE MOLD (CGM)
6. SEE NEXT PAGE FOR PIN GATE MOLD (PGM) OPTION

pk071_01_022614

Figure 1: Corner Gate Mold Option, FG320/FGG320 Package



pk071_02_022614

Figure 2: Pin Gate Mold Option, FG320/FGG320 Package

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
03/13/2014	1.3	Added Figure 2 , pin gate mold package as described in XCN12023 .

Notice of Disclaimer

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